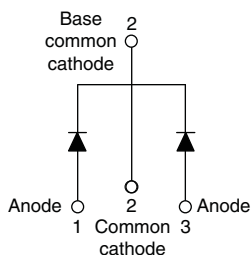
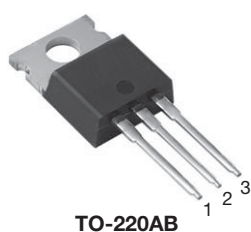


# High Performance Schottky Rectifier, 2 x 15 A



## FEATURES

- 175 °C  $T_J$  operation
- Low forward voltage drop
- High frequency operation
- High purity, high temperature epoxy encapsulation for enhanced mechanical strength and moisture resistance
- Guard ring for enhanced ruggedness and long term reliability
- AEC-Q101 qualified, meets JESD 201, class 2 whisker test
- Material categorization: for definitions of compliance please see [www.vishay.com/doc?99912](http://www.vishay.com/doc?99912)



**RoHS**  
COMPLIANT  
HALOGEN  
**FREE**

## PRIMARY CHARACTERISTICS

$I_{F(AV)}$	2 x 15 A
$V_R$	80 V
$V_F$ at $I_F$	0.67 V
$I_{RM}$ max.	7.0 mA at 125 °C
$T_J$ max.	175 °C
$E_{AS}$	7.50 mJ
Package	TO-220AB
Circuit configuration	Common cathode

## DESCRIPTION

The center tap Schottky rectifier series has been optimized for low reverse leakage at high temperature. The proprietary barrier technology allows for reliable operation up to 175 °C junction temperature. Typical applications are in switching power supplies, converters, freewheeling diodes, and reverse battery protection.

## MAJOR RATINGS AND CHARACTERISTICS

SYMBOL	CHARACTERISTICS	VALUES	UNITS
$I_{F(AV)}$	Rectangular waveform	30	A
$V_{RRM}$		80	V
$I_{FSM}$	$t_p = 5 \mu s$ sine	850	A
$V_F$	15 A <sub>pk</sub> , $T_J = 125$ °C (per leg)	0.67	V
$T_J$	Range	-55 to +175	°C

## VOLTAGE RATINGS

PARAMETER	SYMBOL	VS-30CTQ080HN3	UNITS
Maximum DC reverse voltage	$V_R$	80	V
Maximum working peak reverse voltage	$V_{RWM}$		

## ABSOLUTE MAXIMUM RATINGS

PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS
Maximum average forward current, see fig. 5	$I_{F(AV)}$	50 % duty cycle at $T_C = 129$ °C, rectangular waveform	30 15	A
Maximum peak one cycle non-repetitive surge current per leg, see fig. 7	$I_{FSM}$	5 $\mu s$ sine or 3 $\mu s$ rect. pulse 10 ms sine or 6 ms rect. pulse	850 275	A
Non-repetitive avalanche energy per leg	$E_{AS}$	$T_J = 25$ °C, $I_{AS} = 0.50$ A, $L = 60$ mH	7.50	mJ
Repetitive avalanche current per leg	$I_{AR}$	Current decaying linearly to zero in 1 $\mu s$ Frequency limited by $T_J$ maximum $V_A = 1.5 \times V_R$ typical	0.50	A

**ELECTRICAL SPECIFICATIONS**

PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS
Maximum forward voltage drop per leg See fig. 1	$V_{FM}^{(1)}$	15 A	0.86	V
		30 A	1.05	
		15 A	0.67	
		30 A	0.82	
Maximum reverse leakage current per leg See fig. 2	$I_{RM}^{(1)}$	$T_J = 25\text{ }^{\circ}\text{C}$	0.55	mA
		$T_J = 125\text{ }^{\circ}\text{C}$	7.0	
Maximum junction capacitance per leg	$C_T$	$V_R = 5\text{ }V_{DC}$ (test signal range 100 kHz to 1 MHz) $25\text{ }^{\circ}\text{C}$	500	pF
Typical series inductance per leg	$L_S$	Measured lead to lead 5 mm from package body	8.0	nH
Maximum voltage rate of change	$dV/dt$	Rated $V_R$	10 000	V/ $\mu$ s

**Note**(1) Pulse width < 300  $\mu$ s, duty cycle < 2 %**THERMAL - MECHANICAL SPECIFICATIONS**

PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS
Maximum junction and storage temperature range	T <sub>J</sub> , T <sub>Stg</sub>		-55 to +175	°C
Maximum thermal resistance, junction to case per leg	R <sub>thJC</sub>	DC operation	3.25	°C/W
Maximum thermal resistance, junction to case per package			1.63	
Typical thermal resistance, case to heatsink	R <sub>thCS</sub>	Mounting surface, smooth, and greased	0.50	
Approximate weight			2	g
			0.07	oz.
Mounting torque			6 (5)	kgf · cm (lbf · in)
			12 (10)	
Marking device		Case style TO-220AB	30CTQ080H	

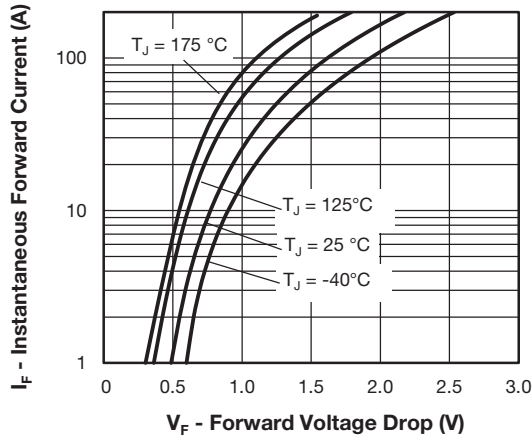


Fig. 1 - Maximum Forward Voltage Drop Characteristics (Per Leg)

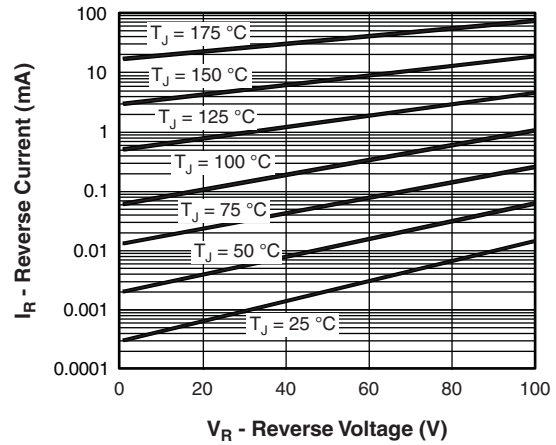


Fig. 2 - Typical Values of Reverse Current vs. Reverse Voltage (Per Leg)

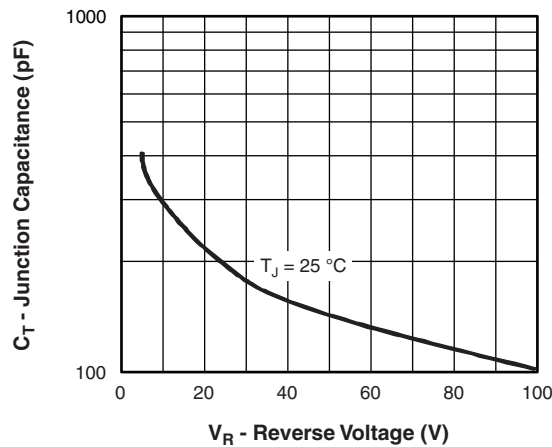
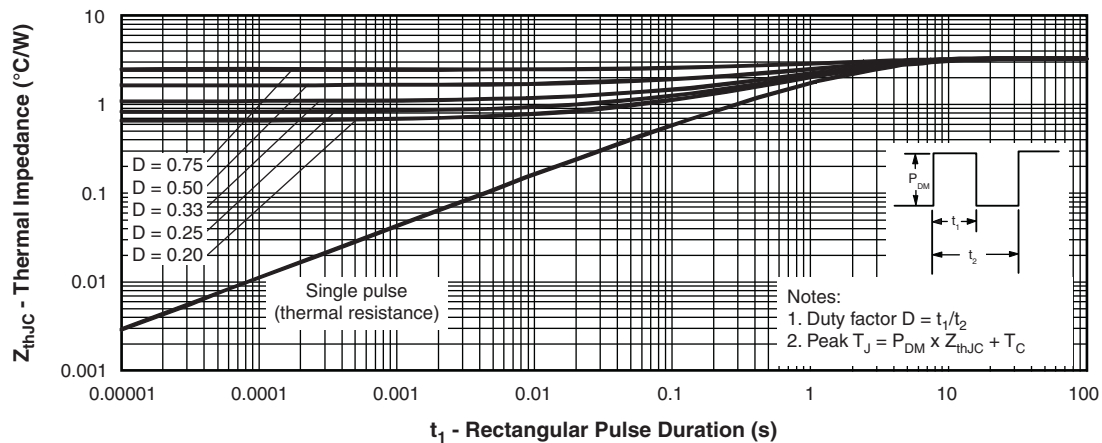


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage (Per Leg)


Fig. 4 - Maximum Thermal Impedance  $Z_{thJC}$  Characteristics (Per Leg)

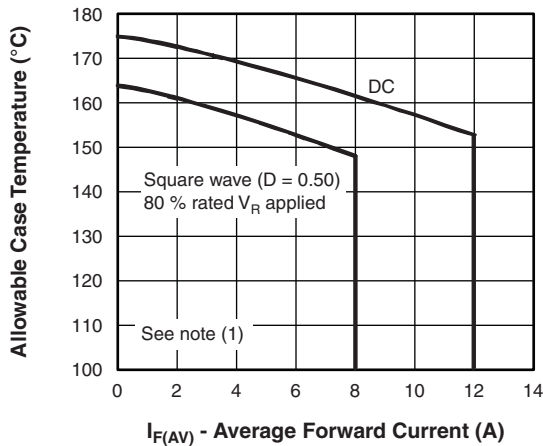


Fig. 5 - Maximum Allowable Case Temperature vs. Average Forward Current (Per Leg)

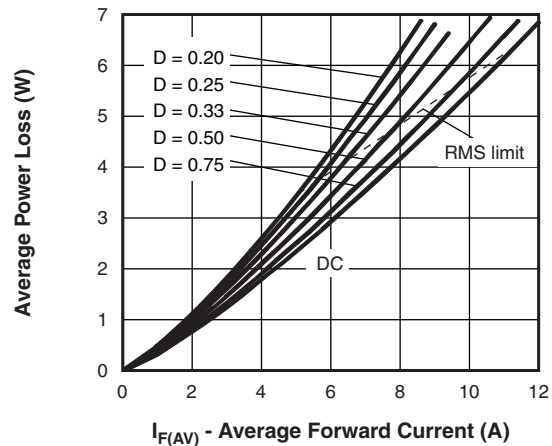


Fig. 6 - Forward Power Loss Characteristics (Per Leg)

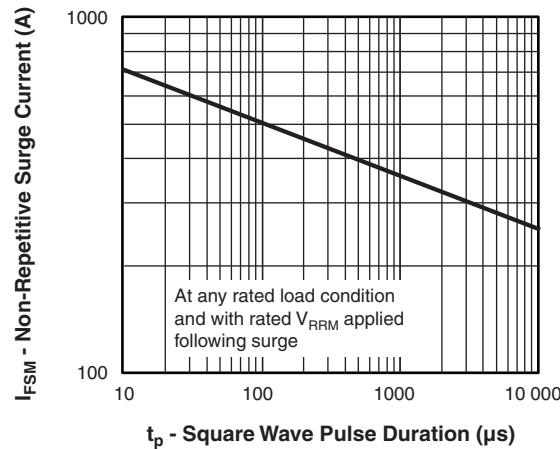


Fig. 7 - Maximum Non-Repetitive Surge Current (Per Leg)

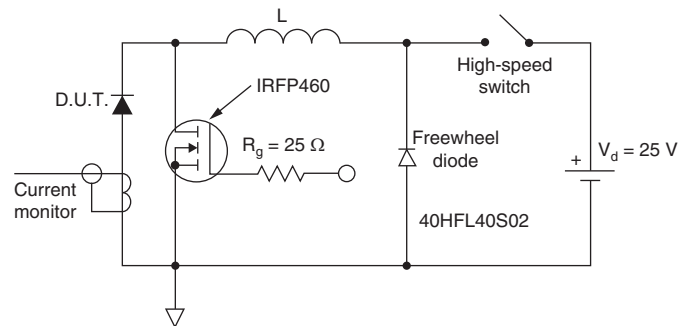


Fig. 8 - Unclamped Inductive Test Circuit

#### Note

- (1) Formula used:  $T_C = T_J - (P_d + P_{dREV}) \times R_{thJC}$ ;  
 $P_d$  = forward power loss =  $I_{F(AV)} \times V_{FM}$  at  $(I_{F(AV)}/D)$  (see fig. 6);  
 $P_{dREV}$  = inverse power loss =  $V_{R1} \times I_R (1 - D)$ ;  $I_R$  at  $V_{R1} = 10\text{ V}$



## ORDERING INFORMATION TABLE

Device code	VS-	30	C	T	Q	080	H	N3
	1	2	3	4	5	6	7	8

- 1** - Vishay Semiconductors product
- 2** - Current rating (30 = 30 A)
- 3** - Circuit configuration:  
C = common cathode
- 4** - Package:  
T = TO-220
- 5** - Schottky "Q" series
- 6** - Voltage ratings 80 = 80 V
- 7** - H = AEC-Q101 qualified
- 8** - Environmental digit  
-N3 = halogen-free, RoHS-compliant, and totally lead (Pb)-free

### ORDERING INFORMATION (Example)

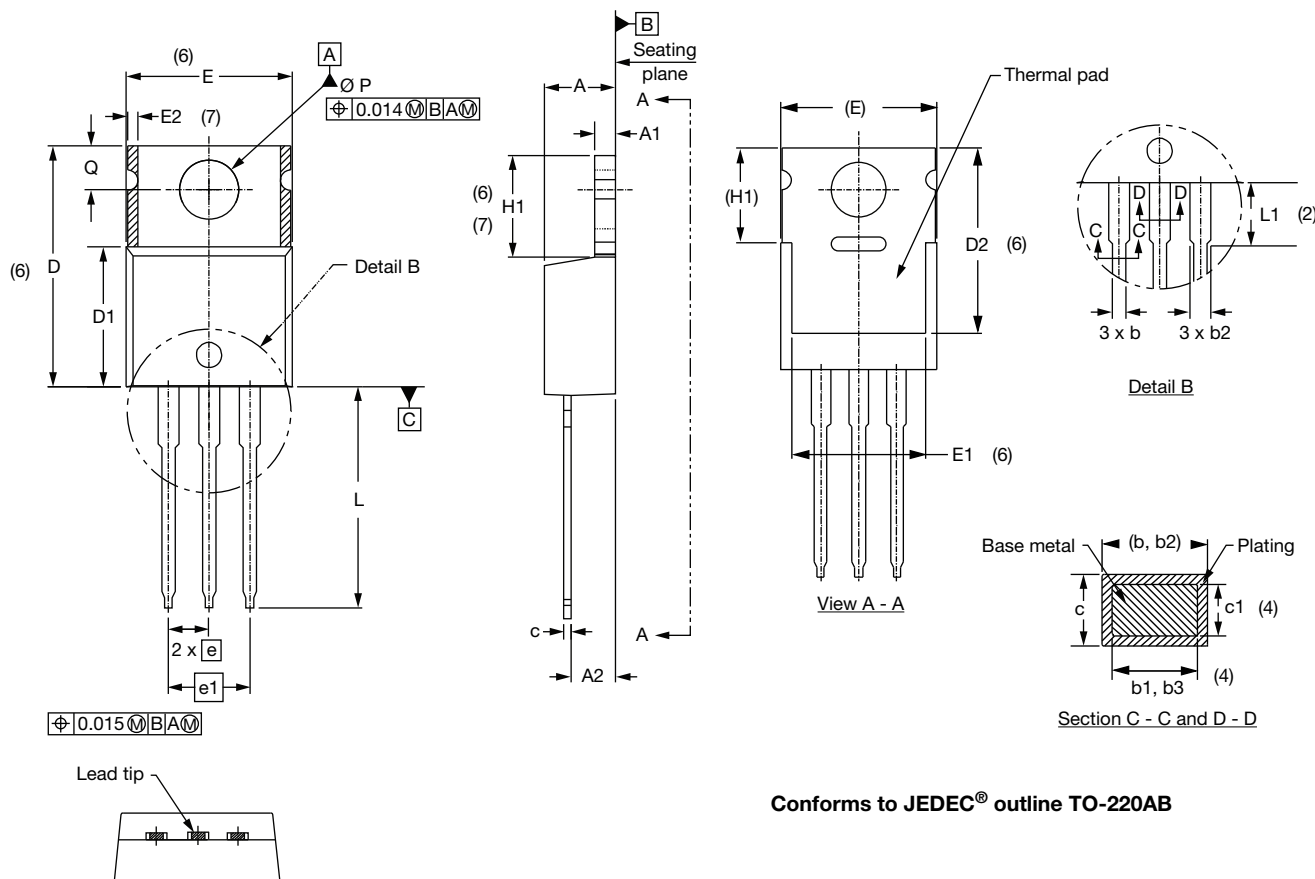
PREFERRED P/N	QUANTITY PER T/R	MINIMUM ORDER QUANTITY	PACKAGING DESCRIPTION
VS-30CTQ080HN3	50	1000	Antistatic plastic tube

### LINKS TO RELATED DOCUMENTS

Dimensions	<a href="http://www.vishay.com/doc?95222">www.vishay.com/doc?95222</a>
Part marking information	<a href="http://www.vishay.com/doc?95028">www.vishay.com/doc?95028</a>

# TO-220AB

**DIMENSIONS** in millimeters and inches



**Conforms to JEDEC® outline TO-220AB**

SYMBOL	MILLIMETERS		INCHES		NOTES
	MIN.	MAX.	MIN.	MAX.	
A	4.25	4.65	0.167	0.183	
A1	1.14	1.40	0.045	0.055	
A2	2.56	2.92	0.101	0.115	
b	0.69	1.01	0.027	0.040	
b1	0.38	0.97	0.015	0.038	4
b2	1.20	1.73	0.047	0.068	
b3	1.14	1.73	0.045	0.068	4
c	0.36	0.61	0.014	0.024	
c1	0.36	0.56	0.014	0.022	4
D	14.85	15.25	0.585	0.600	3
D1	8.38	9.02	0.330	0.355	

## Notes

- (1) Dimensioning and tolerancing as per ASME Y14.5M-1994
- (2) Lead dimension and finish uncontrolled in L1
- (3) Dimension D, D1 and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outermost extremes of the plastic body
- (4) Dimension b1, b3 and c1 apply to base metal only
- (5) Controlling dimensions: inches
- (6) Thermal pad contour optional within dimensions E, H1, D2 and E1
- (7) Dimensions E2 x H1 define a zone where stamping and singulation irregularities are allowed
- (8) Outline conforms to JEDEC® TO-220, except A2 (maximum) and D2 (minimum) where dimensions are derived from the actual package outline



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